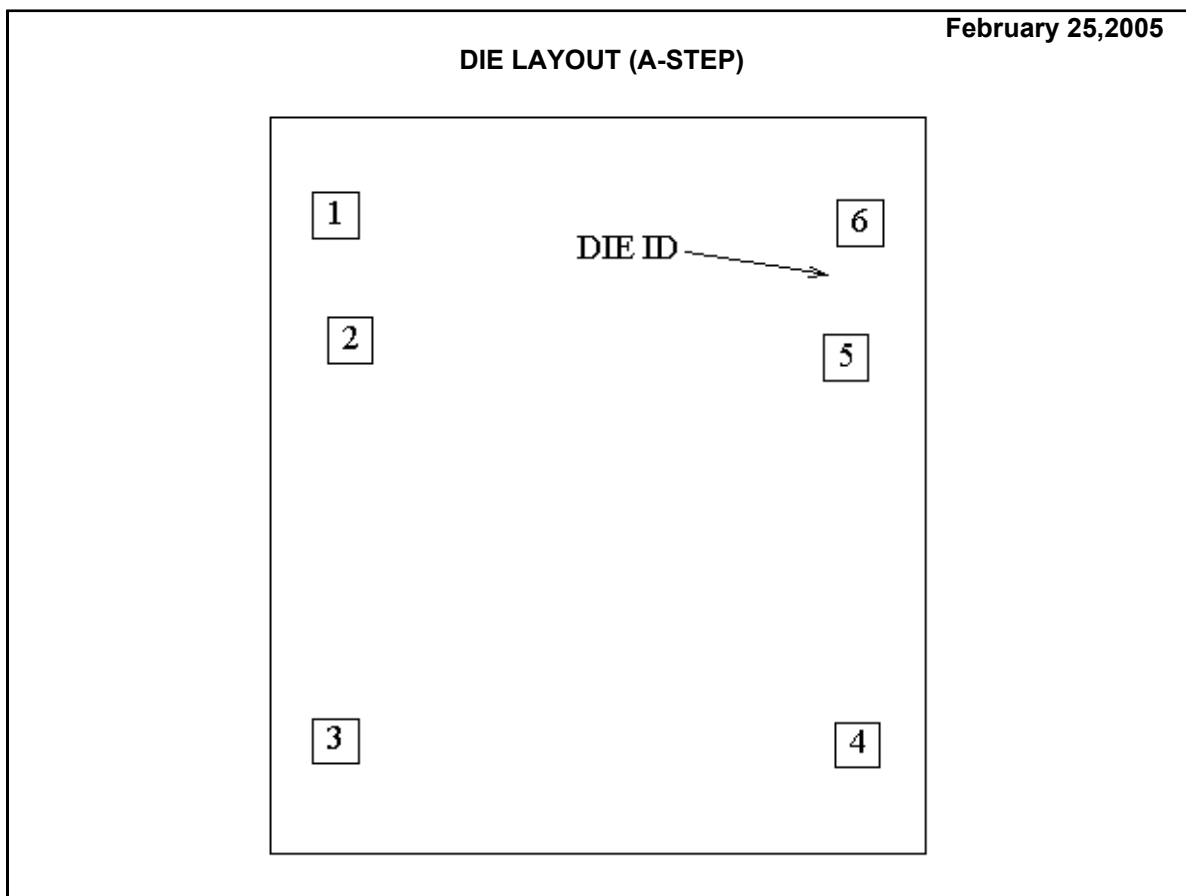


LM74A-5 MDA
SPI/MICROWIRE 12-BIT PLUS SIGN TEMPERATURE SENSOR



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM74A	Bond Pad Opening Size (min)	98μm x 98μm
Die Step	A	Bond Pad Metalization	Al_0.5%Cu
Physical Attributes		Passivation	NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1600μm x 1422μm 63.0mils x 56.0mils	Back Side Connection	GND
Thickness	406μm Nominal		
Min Pitch	270μm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron. Bond Pad Metal: Composition; Al, 0.5% Cu, Thickness; 7000A

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Die Bond Pad Coordinate Locations (A -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
SI/O	1	-569	585	98	X	98
SC	2	-537	314	98	X	98
GND	3	-569	-554	98	X	98
NC	4	563	-562	98	X	98
/CS	5	537	277	98	X	98
V+	6	569	569	98	X	98

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